Title (en)

SPUTTERING DEVICE

Title (de)

Sputtervorrichtung

Title (fr)

DISPOSITIF DE PULVERISATION

Publication

EP 0707663 A1 19960424 (EN)

Application

EP 94921324 A 19940617

Priority

- US 9406908 W 19940617
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Abstract (en)

[origin: WO9500677A1] A sputter coating system (10) employing a vacuum chamber (1). A movable surface (2) is provided within the chamber which is adapted for mounting substrates (3) and moving them thereon. At least one magnetron sputtering device (5) is positioned at a work station adjacent to the substrate holder and adapted for sputtering at least a selected material onto the substrate. At least a second device (6) is positioned adjacent the first device for providing a plasma (11) for enhancing the plasma formed by the first device.

IPC 1-7

C23C 14/34

IPC 8 full level

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CPC (source: EP)

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